



PART NO. : TG49-1505NXRL

FOUR-PORT T1/E1 ISOLATION MODULE

RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

EXTENDED OPERATING TEMPERATURE $-40/+85^{\circ}\text{C}$

ELECTRICAL SPECIFICATIONS @25° C

URNS RATIO

P1-3:P40-39,P6-8:P35-34, 1CT:2 $\pm 2\%$

P11-13:P30-29,P16-18:P25-24

P4-5:38-36,P9-10:P33-31, 1:2CT $\pm 2\%$

P14-15:P28-26,P19-20:P23-21

ACL

1.5mH typ

P1-3,P4-5,P6-8,P9-10,

P11-13,P14-15,P16-18,P19-20

DCR

0.8 Ω max

P1-3,P4-5,P6-8,P9-10,

P11-13,P14-15,P16-18,P19-20

LL

0.5 μH max

P1-3,P4-5,P6-8,P9-10,

P11-13,P14-15,P16-18,P19-20

Cw/w

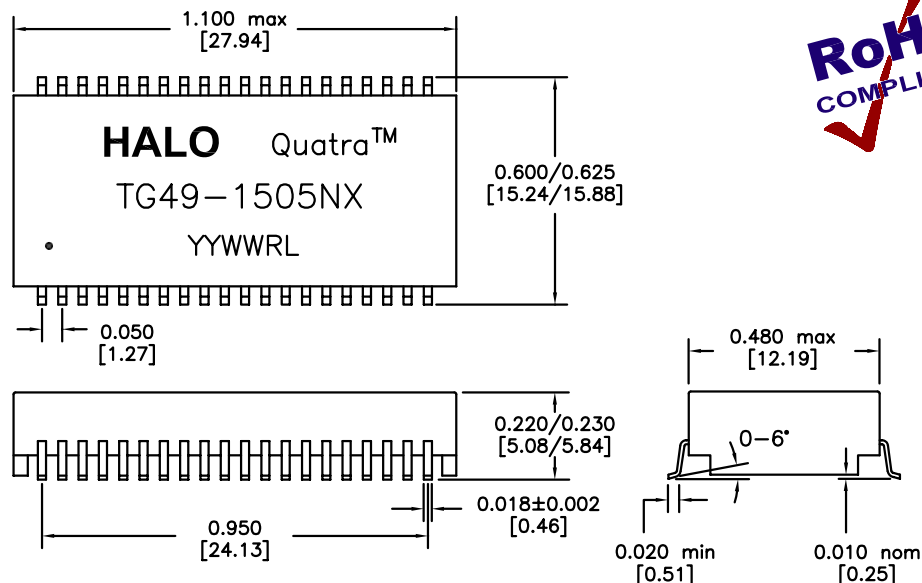
35pF max

CROSSTALK 0.5-5MHz

-60dB typ

ISOLATION

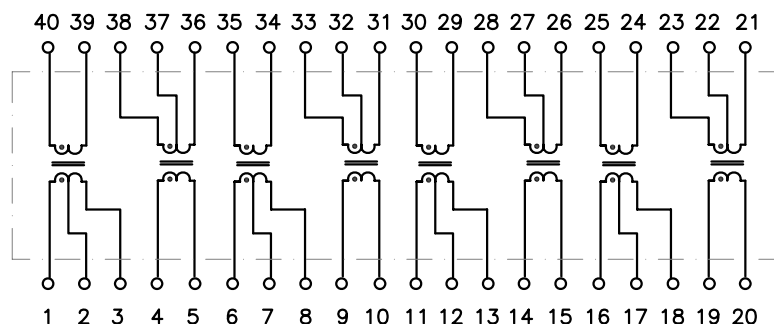
1,500Vrms



DIMENSIONS: Inch [mm]

CO-PLANARITY: 0.004 [0.10]

TOLERANCES: ± 0.005 INCH IF NOT SPECIFIED



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE ISOLATION MODULE

FOR T1/E1

PART NO. TG49-1505NXRL

SCALE NONE

PAGE 1 OF 2

SIGNATURES

DRAWN LI ZHI ZHONG

CHECKED LEI KEONG

APPROVED PETER LU

FILE TG49NXRL.DWG

DATE

11/29/05

3/23/11

3/23/11

REV.

A

B

DESC.

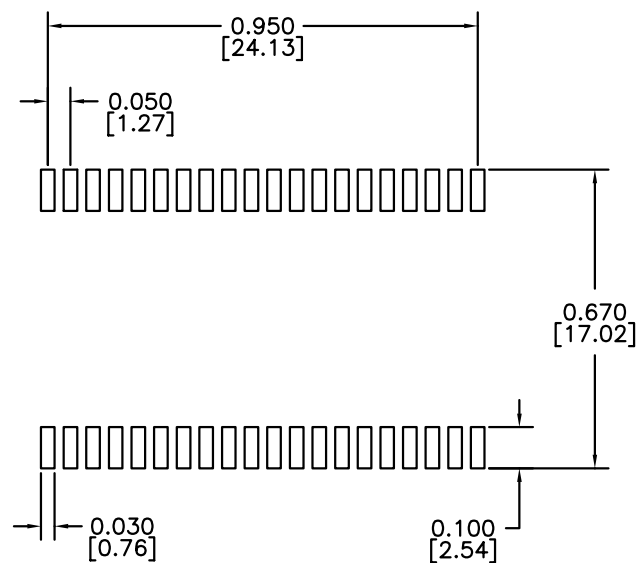
FIRST ISSUE

PROD. RELEASE

DATE

11/29/05

3/23/11



RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
FOR	T1/E1		DRAWN LI ZHI ZHONG	11/29/05	A	FIRST ISSUE	11/29/05
PART NO.	TG49-1505NXRL		CHECKED LEI KEONG	3/23/11	B	PROD. RELEASE	3/23/11
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